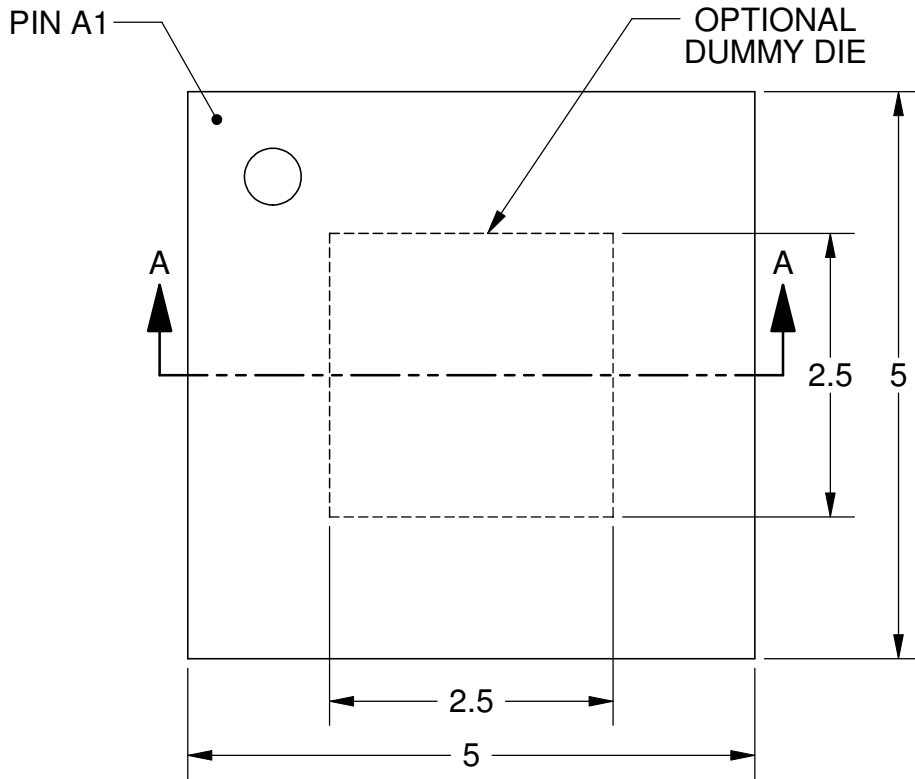
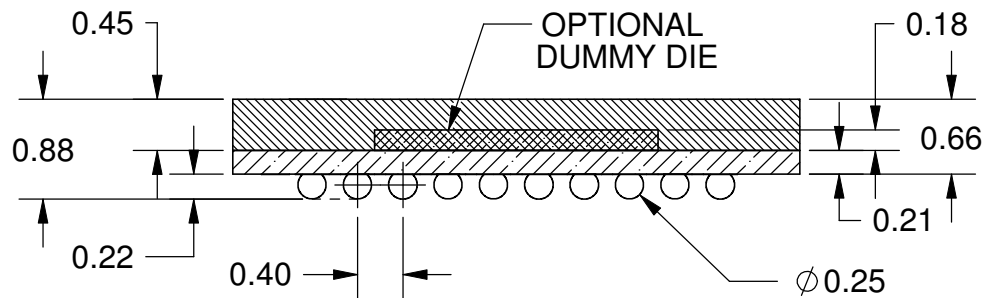
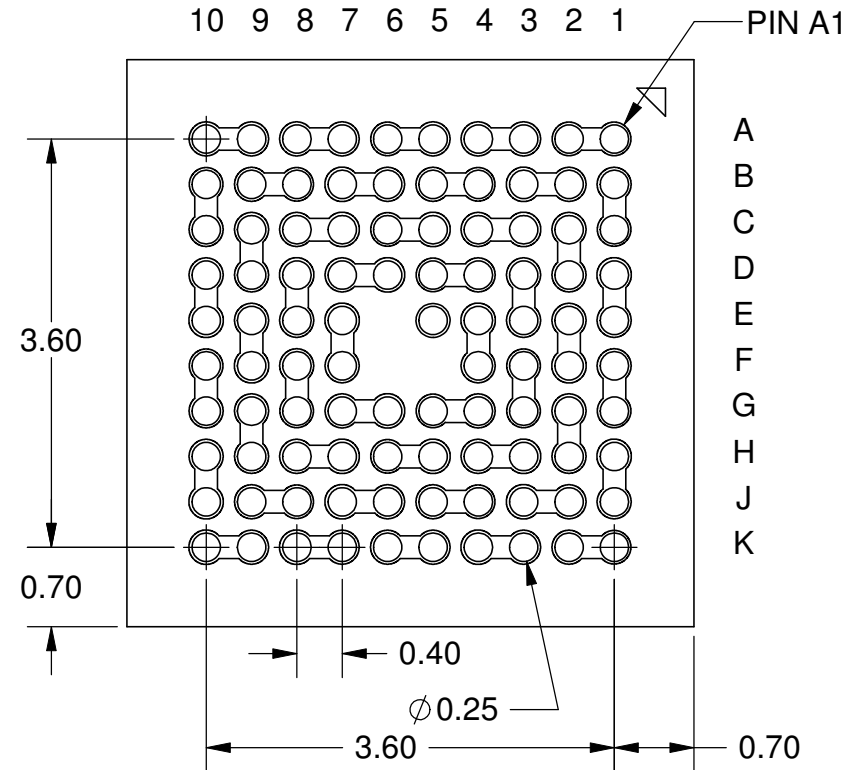


TOP VIEW



BALL VIEW




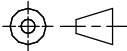
SECTION A-A

Notes: (Unless Otherwise Specified).

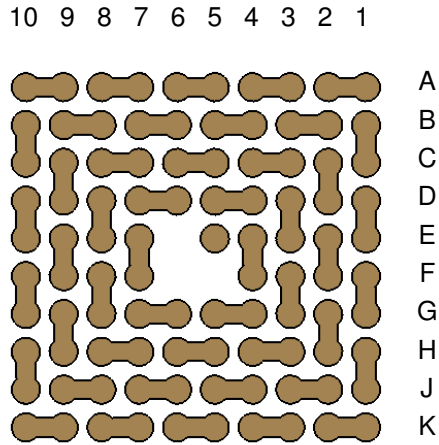
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.20mm.
- 5) PAD Cu DIAMETER: 0.30mm.
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

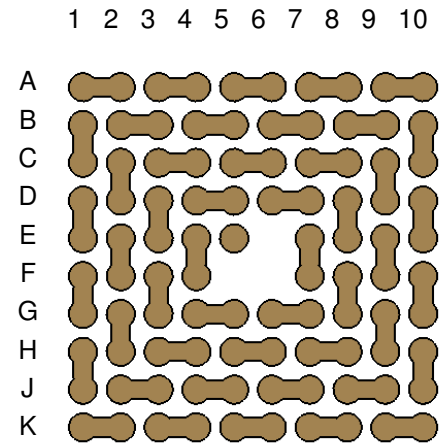
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA97T.4C-DC107	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
BGA97T.4C-DC107D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA97T.4-DC107	Sn63/Pb37	NO	NO	NO
BGA97T.4-DC107D	Sn63/Pb37	NO	NO	YES

TOLERANCE UNLESS NOTED		APPROVALS	DATE				
X.X	+/- 0.10	DRAWN J. Hines	6/17/2011				
X.XX	+/- 0.05						
X.XXX	+/- 0.025						
ANGLES +/- 0.5°		ENG		SCALE 15:1			
ALL DIMENSIONS IN		MFG					
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		QA		DO NOT SCALE DRAWING			
THIRD ANGLE PROJECTION		CUST					
		REVISED					

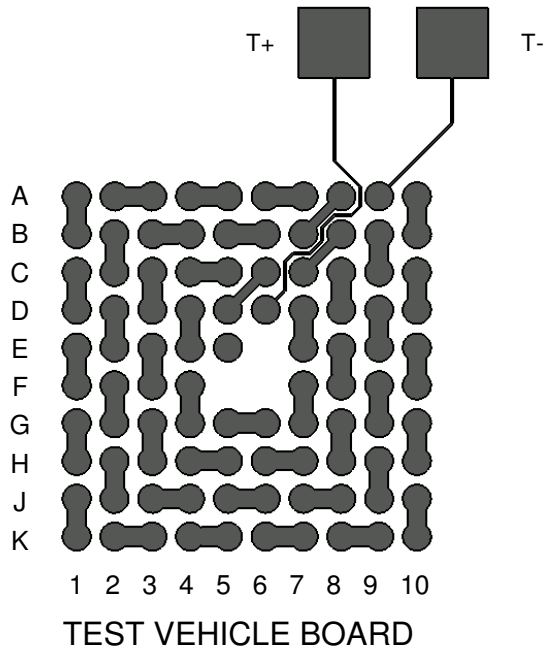
BALL VIEW



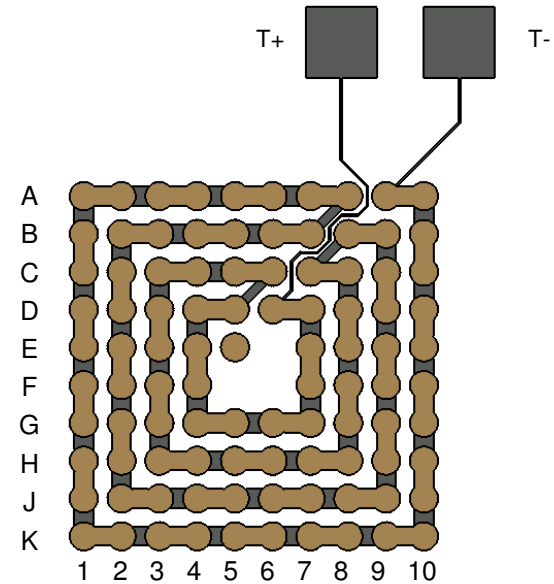
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.30mm (11.8mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.20mm (7.8mil).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.20mm (7.8mil).

TopLine ®			
TITLE		BGA97T.4C-DC107D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
12.5:1	A	541073	A
DO NOT SCALE DRAWING			SHEET 2 OF 2

